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FDC6401N

Dual N-Channel 2.5V Specified PowerTrench® MOSFET

General Description

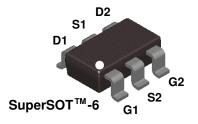
This Dual N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low R_{DS(ON)} and fast switching speed.

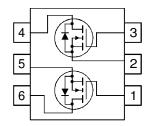
Applications

- DC/DC converter
- Battery Protection
- Power Management

Features

- 3.0 A, 20 V. $R_{DS(ON)} = 70 \ m\Omega \ @ \ V_{GS} = 4.5 \ V$ $R_{DS(ON)} = 95 \ m\Omega \ @ \ V_{GS} = 2.5 \ V$
- Low gate charge (3.3 nC)
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS(ON)}}$
- · High power and current handling capability





Absolute Maximum Ratings T_{A=25°C} unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±12	V
I _D	Drain Current - Continuous	(Note 1a)	3.0	Α
	– Pulsed		12	
P _D	Power Dissipation for Single Operation	(Note 1a)	0.96	W
		(Note 1b)	0.9	
		(Note 1c)	0.7	
T_J , T_{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	130	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	60	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.401	FDC6401N	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics	1			I	I
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	20			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		13		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 16 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			1	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 12 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			-100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V}$ $V_{DS} = 0 \text{ V}$			100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.5	0.9	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-3		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = 4.5 \text{ V},$ $I_D = 3.0 \text{ A}$ $V_{GS} = 2.5 \text{ V},$ $I_D = 2.5 \text{ A}$ $V_{GS} = 4.5 \text{ V},$ $I_D = 3.0 \text{ A},$ $I_{J} = 125 ^{\circ}\text{C}$		50 66 71	70 95 106	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, I_D = 3.0 \text{ A}, T_J = 125^{\circ}\text{C}$ $V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$	12			Α
9 FS	Forward Transconductance	$V_{DS} = 5V$, $I_{D} = 3.0 \text{ A}$		10		S
Dvnamio	Characteristics	•				
C _{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		324		pF
Coss	Output Capacitance	f = 1.0 MHz		82		рF
C _{rss}	Reverse Transfer Capacitance			42		pF
Switchin	g Characteristics (Note 2)	•				
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 10 \text{ V}, \qquad I_{D} = 1 \text{ A},$		5	10	ns
t _r	Turn-On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$		7	14	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time			13	23	ns
t _f	Turn-Off Fall Time			1.6	3	ns
$\overline{Q_g}$	Total Gate Charge	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 3.0 \text{ A},$		3.3	4.6	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 4.5 V		0.95		nC
Q_{gd}	Gate-Drain Charge	1		0.7		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings	•	•	•	
Is	Maximum Continuous Drain-Source				0.8	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.8 A (Note 2)		0.7	1.2	V

Notes:

^{1.} $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 130 °C/W when mounted on a 0.125 in² pad of 2 oz. copper.



b) 140 °C/W when mounted on a .004 in² pad of 2 oz copper



c) 180 C°/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Typical Characteristics

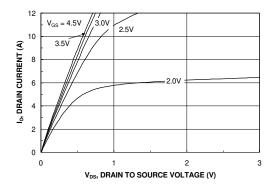


Figure 1. On-Region Characteristics.

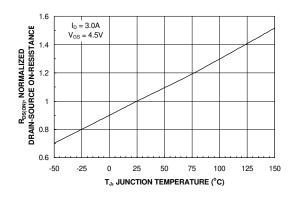


Figure 3. On-Resistance Variation with Temperature.

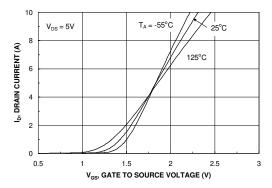


Figure 5. Transfer Characteristics.

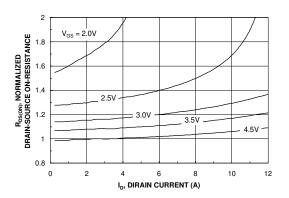


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

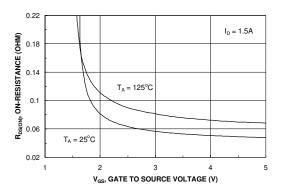


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

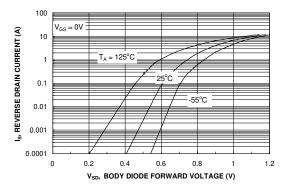
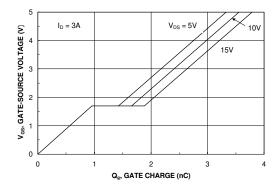


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



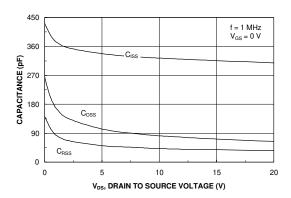
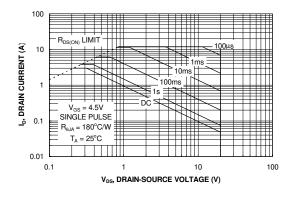


Figure 7. Gate Charge Characteristics.





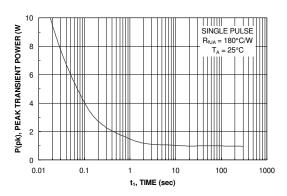


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

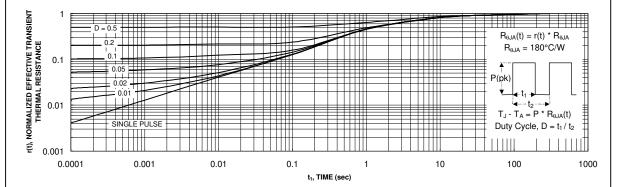


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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